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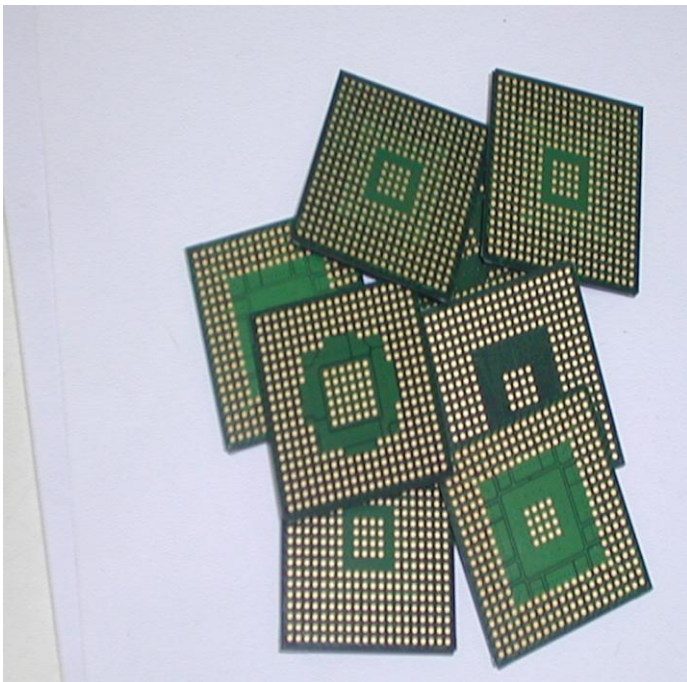
SOLDERING PLACEMENT' SYSTEM 錫球植入機-BU-510

植球能力: $0.4\Phi\sim 0.76\Phi$ 植球範圍:L-60mm . W-80mm



各類BGA-植球

真空清除錫球座(清球配備)



維修設備

錫球植入機

BGA rework equipment --- Solder ball placement system BU-510

(1)外部尺寸 :75cm(L),X 25cm(W),X 26cm(H)

■ Outside dimension: 75cm(L), 25cm(W), 26cm(H).

(2)重量 : 28.7 kg.

■ Weight: 28.7 kg.

(3)使用電壓 : 110/220V 50/60Hz.

■ Working voltage: 110/220V;50/60Hz

(4)使用氣壓 : 6 kg/cm².

■ Working air pressure: 6 kg/cm².

(5)錫球規格 :依 BGA 不同使用錫球規格而異.

■ Solder ball specification: According to the solder ball spec being used by different kinds of BGA package.

(6)BGA 模具 :依 BGA 不同規格 SIZE 可更換需求 BGA 模具.

■ BGA IC holder: It is available for changing-over different types of BGA IC holders according to different size or spec of BGA package.

(7) BGA 模具 :依 BGA 不同規格 SIZE 可更換需求錫球模具.

■ Solder ball screening fixture: It is available for changing-over different ball screening fixtures according to different size or spec of solder ball.

(8)錫球植入速度: 錫球植入 BGA-PAD 點可微調控制錫球植入速度.

■ Solder ball placing speed: The speed for placing solder balls onto BGA pads can be adjusted and fine-tuning controlled.

(9)錫球植入率:百分之 98.

■ Ball-placing yield rate: 98%.

(10)錫球植入精度:0.03 mm.

■ Ball-placing accuracy: 0.03mm.

(11)模具槽退料:退料速度 30 - 300 mm/S.

■ BGA IC holder unloading speed: Unloading speed 30~300 mm/s.

(12)自動植球時間:22/sec

■ Automatic ball-placing operation cycle time : 22 seconds.

再造

BGA

regeneration!

以低廉錫球 重新植入再造完整

~ Place solder balls on BGA to regenerate a whole new one with the lowest cost. ~
錫球植入機,未拆下 BGA 重新植入全新錫球,以利重新回焊維修,本設備提供 SMT 業界進入 BGA 作業技術層次的提升,本機為 BGA 生產作業得力助手.

The solder ball placement system places new solder balls again onto ball removed BGA-IC for new reflowing rework. This equipment provides a technology promotion for traditional BGA operation in SMT industry. It is a very useful tool for BGA production.

本設備榮獲多國專利仿冒必究

[There are patents approved by lots of countries for this equipment. All rights are reserved]

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